

LTM4623 25LD-LGA 6.25mm X 6.25mm X 1.82mm (TABLE OF MATERIAL DECLARATION)							
This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.							
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0362	Barium Compounds	7727-43-7	0.00102	2.81
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2	0.01006	27.77
				Copper Metal	7440-50-8	0.01403	38.73
				Copper Compounds	147-14-8	0.00001	0.02
				**Ecotoxic substances	7440-38-2 7440-28-0	0.00000	0.00
				Gold metal or alloy	7440-57-5	0.00009	0.25
				Nickel	7440-02-0	0.00071	1.95
				Zinc	7440-66-6	0.00001	0.03
				Continuous Filament Fiber Glass	65997-17-3	0.00791	21.82
				Acrylic Resin	*non-disclosure	0.00192	5.31
				Epoxy Resin	*non-disclosure	0.00007	0.19
				Chromium(III) oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00010	0.27
				Talc;not containing fibers like asbestos	14807-96-6	0.00012	0.32
				Aromatic carbonyl compounds	non-disclosure	0.00011	0.30
				Cyanoguanidine	461-58-5	0.00000	0.01
				Calcium caobonate	471-34-1	0.00001	0.04
				Amine compounds	*non-disclosure	0.00002	0.05
				Leveling agent and others	*non-disclosure	0.00005	0.13
				2	Solder Paste	Alloy	0.0039
Sb	7440-36-0	0.00020	5.00				
3	Passive/Active Components		0.0520	Iron Powder (Fe)	7439-89-6	0.03603	69.28
				Copper (Cu)	7440-50-8	0.01077	20.71
				Nickel (Ni)	7440-02-0	0.00062	1.19
				Tin (Sn)	7440-31-5	0.00045	0.86
				Ceramic (Ba) Compounds	12047-27-7	0.00414	7.95
4	Active Ics	Silicon	0.0016	Silicon	7440-21-3	0.00161	100.00
5	Wire	Gold	0.0007	Au	7440-57-5	0.00067	99.99
6	Encapsulation	Epoxy Resin	0.0804	Fused Silica	60676-86-0	0.06207	77.20
				Epoxy Resin	non-disclosure	0.00716	8.90
				Phenol Resin	non-disclosure	0.00716	8.90
				Crytalline Silica	14808-60-7	0.00241	3.00
				Carbon Black	1333-86-4	0.00040	0.50
				Metal Hydroxide	non-disclosure	0.00121	1.50
Total Package Weight			0.1749				

Note: Composition derived from MSDS and material C of C from Vendors  
 Component Weight based on assembly of generic parts